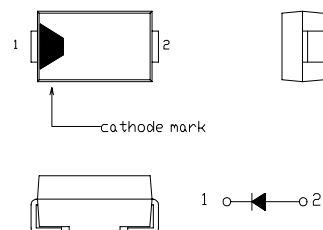


SBD Type : EC31QS10

FEATURES

- * Miniature Size, Surface Mount Device
- * Low Forward Voltage Drop
- * Low Power Loss, High Efficiency
- * High Surge Capability
- * 30 Volts through 100Volts Types Available
- * Packaged in 12mm Tape and Reel
- * Not Rolling During Assembly

OUTLINE DRAWING



Maximum Ratings

Approx Net Weight: 0.06g

| Rating | Symbol | EC31QS10 | | Unit | |
|--------------------------------------|--------------|-------------|---|------------------------------------|---|
| Repetitive Peak Reverse Voltage | V_{RRM} | 100 | | V | |
| Average Rectified Output Current | I_O | 1.3 | Ta=26 °C *1 | 50Hz Half Sine Wave Resistive Load | A |
| | | 3.0 | Tl=84 °C Tl:Lead Temperature | | |
| RMS Forward Current | $I_{F(RMS)}$ | 4.71 | | A | |
| Surge Forward Current | I_{FSM} | 60 | 50Hz Half Sine Wave, 1cycle Non-repetitive | A | |
| Operating Junction Temperature Range | T_{jw} | -40 to +150 | | °C | |
| Storage Temperature Range | T_{stg} | -40 to +150 | | °C | |

Electrical • Thermal Characteristics

| Characteristics | Symbol | Conditions | Min. | Typ. | Max. | Unit |
|----------------------|---------------------|---|------|------|------|------|
| Peak Reverse Current | I_{RM} | $T_j = 25^\circ\text{C}$, $V_{RM} = V_{RRM}$ | - | - | 2 | mA |
| Peak Forward Voltage | V_{FM} | $T_j = 25^\circ\text{C}$, $I_{FM} = 3.0\text{A}$ | - | - | 0.85 | V |
| Thermal Resistance | Junction to Ambient | $R_{th(j-a)}$ | - | - | 108 | °C/W |
| | Junction to Lead | $R_{th(j-l)}$ | - | - | 23 | |

- *1 Alumina Substrate Mounted
Soldering Lands=2x2mm, Both Sides

EC31QS10 OUTLINE DRAWING (Dimensions in mm)

